



PATENT APPLICATION

Inventor: Wen J. Meng
Serial No: 10/660,926
Filing Date: September 12, 2003
Title: Microscale Compression Molding of Metals with Surface Engineered
Liga Inserts
Atty Docket: Meng 0310

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

In accordance with the duty of candor and good faith imposed by 37 C.F.R. §1.56 and means of complying therewith according to 37 C.F.R. §§1.97 and 1.98, the references listed on the attached Information Disclosure Citation are called to the attention of the United States Patent and Trademark Office in connection with the above-identified patent application. Copies of the cited references are enclosed herewith. No admission is made that the cited art represents the prior art or that the cited art is the most material art.

The Office is urged to consider the cited references and to make an independent decision with respect to their materiality.

Respectfully submitted,



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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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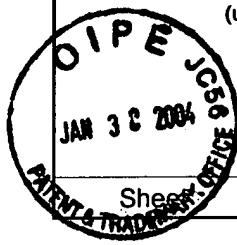
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- Information Disclosure Citation
- Copies of six cited references
- Return postcard verifying receipt of the listed enclosures



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January 27, 2004

Substitute for form 1449A/PTO		U.S. Patent and Trademark Office U.S. Department of Commerce		COMPLETE IF KNOWN		
INFORMATION DISCLOSURE CITATION (use as many sheets as necessary)				Application Number	10/660,926	
				Filing Date	September 12, 2003	
				First Named Inventor	Wen J. Meng	
				Art Unit		
				Examiner Name		
Sheet	1	of	1	Attorney Docket Number	Meng 0310	



U.S. PATENT DOCUMENTS					
Exam. Initial	Document No.	Date	Name	Class	Subcl.

FOREIGN PATENT DOCUMENTS				
Exam. Initial	Foreign Patent Document	Publication Date MM-DD-YY	Name of Patentee or Applicant of Cited Document	Translation ?
	Country Code / Number / Kind			

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)	
	Cao <i>et al.</i> , "Amorphous Hydrocarbon based Thin Films for High-aspect-ratio MEMS Applications," <i>Thin Solid Films</i> , vol. 398/399, pp. 553-559 (2001)
	Cao <i>et al.</i> , "Microscale Compression Molding of Al with Surface Engineered LIGA Inserts," submitted for publication in June 2003
	Cao <i>et al.</i> , "Molding of Pb and Zn with Microscale Mold Inserts," presented at the Materials Research Society Meeting, Boston, Massachusetts (December 2002)
	Harris, C. <i>et al.</i> , "Design and Fabrication of a Cross Flow Micro Heat Exchanger," <i>IEEE J. Microelectromech. Syst.</i> , Vol. 9, no. 4, pp. 502-508 (2000)
	Stephens, L.S. <i>et al.</i> , "A Pin Fin Microheat Sink for Cooling Macroscale Conformal Surfaces Under the Influence of Thrust and Frictional Forces," <i>IEEE J. Microelectromech. Syst.</i> , Vol. 10, no. 2, pp. 222-231 (2001)
	Weber, L. <i>et al.</i> , "Micromolding: a powerful tool for large-scale production of precise microstructures," <i>SPIE Proceeding, Micromachining and Microfabrication Process Technology II</i> , Austin, TX, pp. 156-167 (1996).

EXAMINER SIGNATURE	DATE CONSIDERED
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